FUĴĨTSU

PRIMERGY TX300 S7 PRIMERGY RX350 S7

System configurator and order-information guide

February 2014

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Change report

PRIMERGY Server

Instructions

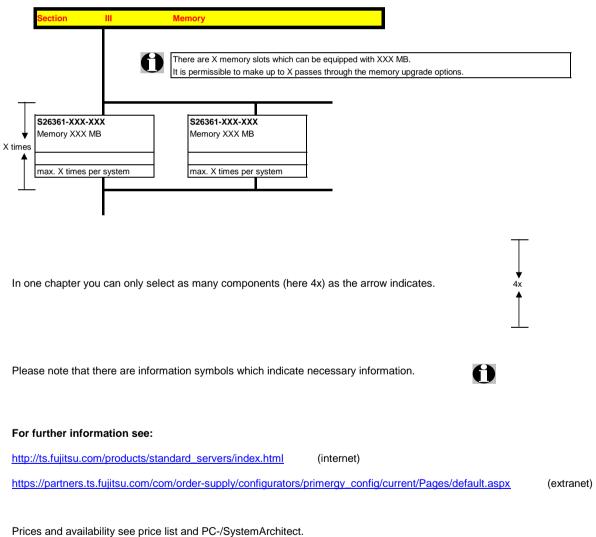
This document contains basic product and configuration information that will enable you to configure your system via PC-/SystemArchitect.

Only these tools will ensure a fast and proper configuration of your PRIMERGY server or your complete PRIMERGY Rack system.

You can configure your individual PRIMERGY server in order to adjust your specific requirements.

The System configurator is divided into several chapters that are identical to the current price list and PC-/SystemArchitect.

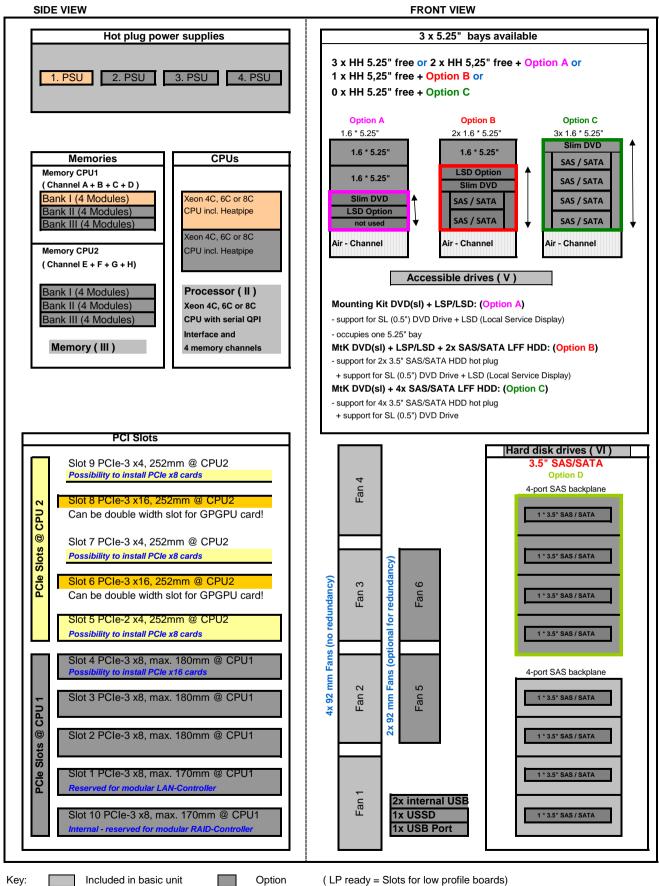
Please follow the lines. If there is a junction, you can choose which way or component you would like to take. Go through the configurator by following the lines from the top to the bottom.



Subject to change and errors excepted.

Configuration diagram PRIMERGY

System unit (3.5" HDDs)



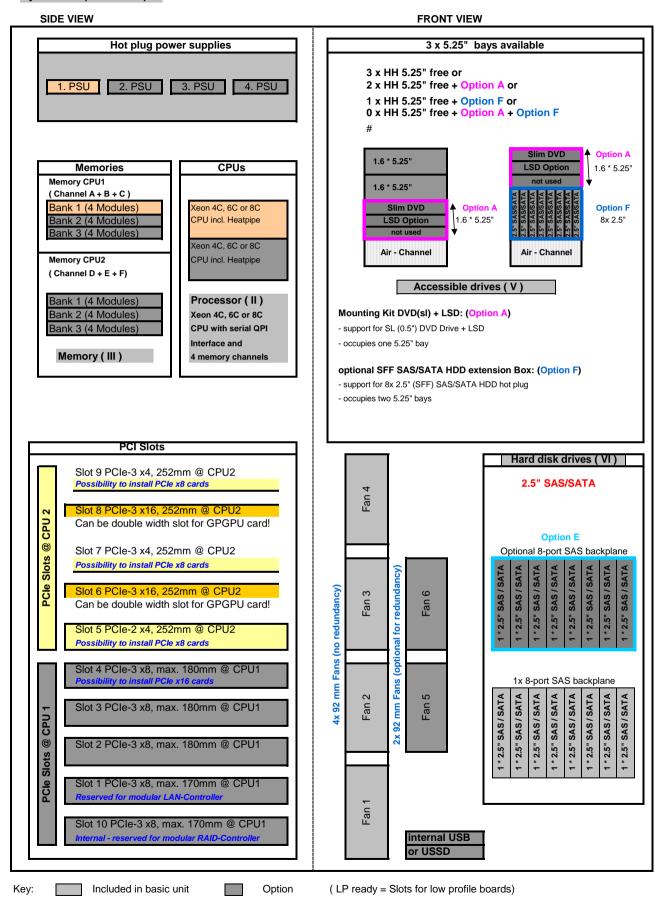
Option

(LP ready = Slots for low profile boards)

One CPU, one memory per CPU and one PSU has to be selected for an orderable basic unit.

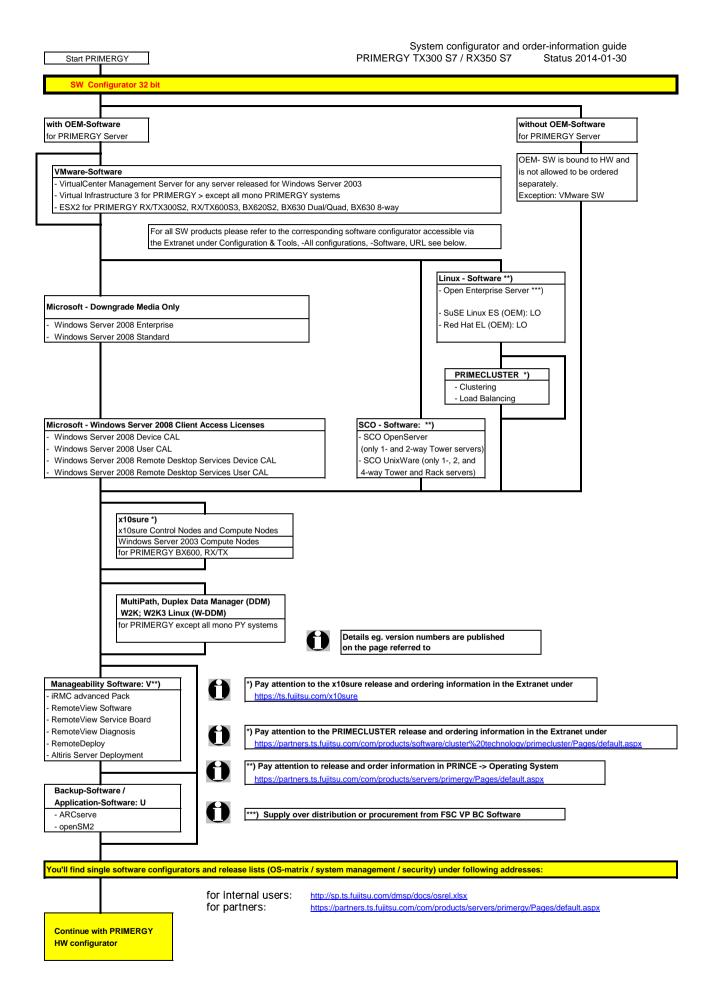
Configuration diagram PRIMERGY

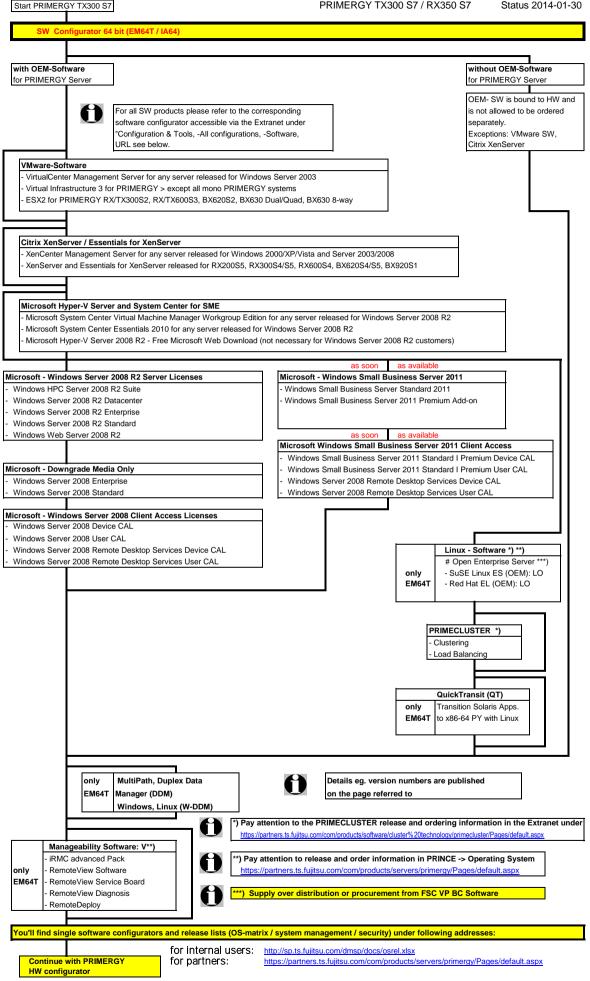
System unit (2.5" HDDs)



One CPU, one memory per CPU and one PSU has to be selected for an orderable basic unit.

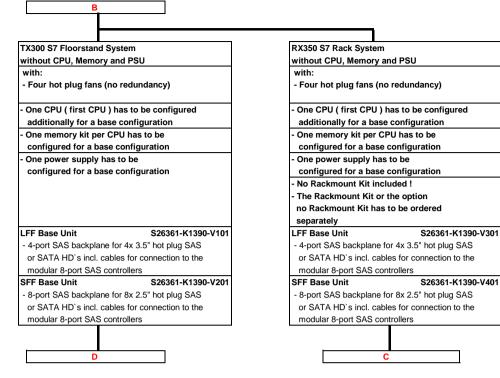
Fujitsu PRIMERGY Server

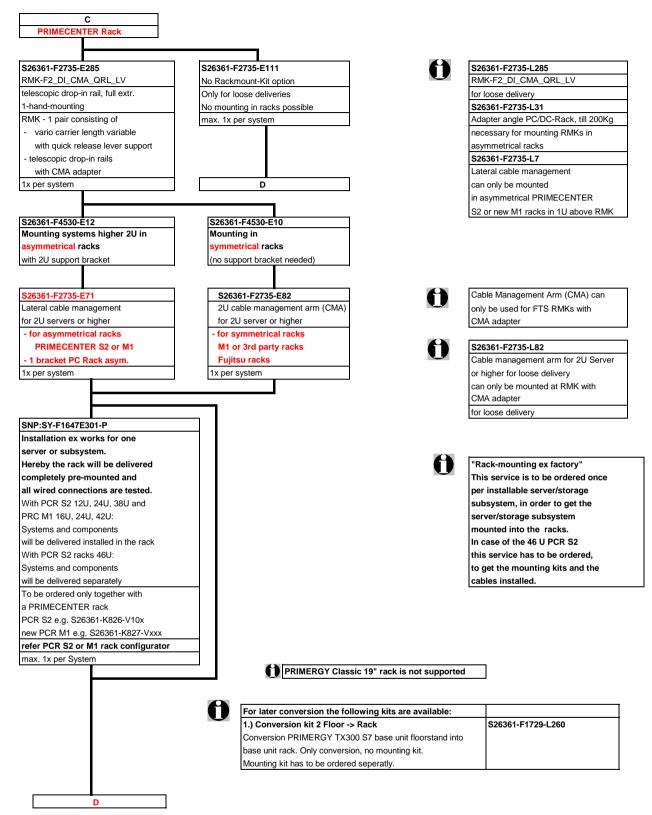


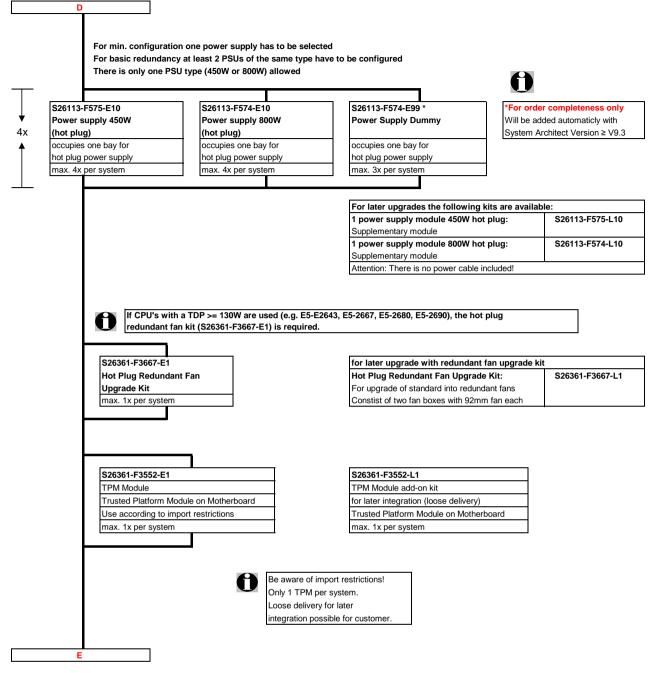


art PRIMERGY TX300 S7		s 2014-0
ction	Basic units	
	040. Out on the line of the second se	
	SAS - System unit, Rack and Floorstand including:	
	* By a key lockable front bezel in floorstand version * Basic units with:	
	- 4 Hot-Plug Power Supply Slots	
	- 4 Standard Fans (92mm; no redundancy)	
	 12 memory DIMMs per CPU (max 384GB) => Total 24 DIMMs (max 768GB) for two CPU's SAS/ SATA backplane with hot plug bays for 4x 3.5" HDD's or 8x 2.5" HDD's & SSD's 	
	* 3 drive bays 5,25" for accessible drives free available.	
	* Integrated ServerView Diagnostics Technology with an modul for indication of failed	
	components via LED's.	
	Simultaneously components are marked which can be replaced by the customer. This LEDs can be dispalyed during service even without mains connection.	
	Options:	
	* Up to 4 hot plug power supply modules with 450W & 800W	
	* 4x 3.5" or 8x 2.5" HD backplane kits	
	* - Optional modular RAID 0/1 controllers with IME (Integrated Mirroring Enhanced) support	
	based on LSI 1064 or LSI SAS2008 chipset or as alternative	
	- optional modular RAID 5 controller based on LSI SAS2108 chipset	
	* One 0,5" bay can be configured with an optional LC- display for LocalView in a drawer	
	Systemboard D2649 with:	
	* Up to two Xeon 4C, 6C & 8C CPU's (Socket-R) with 2 serial QPI links (Quick Path Interconnect) and four memory channels per CPU	
	First CPU has to be selected for an orderable basic unit,	
	* Chipset Intel® C600 Series (codenamed Patsburg)	
	* 10 PCI slots:	
	@ first CPU - 4x PCIe-3 x8 (one notched to install x16 cards)	
	@ first CPU - 1x PCIe-3 x8 (for internal modular RAID controller only)	
	@ second CPU - 2x PCIe-3 x16	
	@ second CPU - 2x PCIe-3 x4 @ second CPU - 1x PCIe-2 x4	
	* 24 memory slots for max. 768GB RAM DDR3 available	
	- Memory is divided into 12 DIMMs per CPU (4 channels with 3 slots per channel)	
	Possible max. configurations are:	
	24x 32GB LRDIMM (quad rank modules) = 768GB 24x 16GB RDIMM (dual rank modules) = 384GB	
	16x 8GB UDIMM (dual rank modules) = 128GB	
	First Memory (one module) has to be selected for an orderable basic unit per CPU	
	- Memory upgrade is possible module wise	
	- Memory mirrroring is supported with 2 identical modules in channel A+B CPU 1 or D+E CPU 2	
	 Rank sparing mode is supported with min. 2x 1R/2R or 1x 4R modules for RDIMM or LRDIMM SDDC (Chipkill) is supported for memory modules, 	
	* Dual Port 10/100/1000 x4 PCI Express* Gigabit Ethernet Intel LAN controller Powerville on-board	
	* iRMC S3 (integrated Remote Management Controller) on-board server management controller with	
	dedicated 10/100/1000 Service LAN-port and integrated graphics controller. The Service LAN-port can be switched alternatively on standard Gbit LAN port 1	
	* Graphics Controller integrated in iRMC S3 (integrated Remote Management Controller):	
	Supported graphical resolutions are: 1920x1200x16bpp, 1920x1080x16bpp, 1600x1200x16bpp, 1680x1050x16bpp, 1440x900x16bpp,	
	1920x1200x16bpp, 1920x1080x16bpp, 1600x1200x16bpp, 1680x1050x16bpp, 1440x900x16bpp, 1440x900x16bpp, 1280x1024x32bpp, 1152x864x16bpp, 1024x768x32bpp, 800x600x32bpp, 640x480x32bpp	

	PRIMERGY TX300 S7 / RX350 S7	Status 201
Interfaces at the rear:		
* 1x RS-232-C (serial, 9 pins) (usable f	or BMC or OS or shared)	
* 1x RS-232-C (serial, 9 pins)		
* 1x VGA (15 pins)		
* 4x USB 2.0 (UHCI) with 480MBit/s,	no USB wakeup	
* 2x LAN RJ45, 1x Service-LAN RJ45		
Interfaces on the front:		
* 2x USB 2.0 (UHCI) with 480MBit/s,	no USB wakeup	
* 1x VGA (15 pins) as an option		
* 1x Service-LAN RJ45 as an option		
Interfaces internal:		
* 2x released internal USB Interfaces for	or backup devices,	
* 1x USB 2.0 (UHCI) with 480MBit/s	for dongle funcionality, no USB wakeup	
* 1x USSD		
Cables:		
* SATA cable for DVD.		
* 2x SAS cables for connection of 4 SA	S-ports each incl. signaling	
* ServerView Suite Software package i	ncl. ServerStart, ServerBooks, Management Software and Update	es
	CD)	

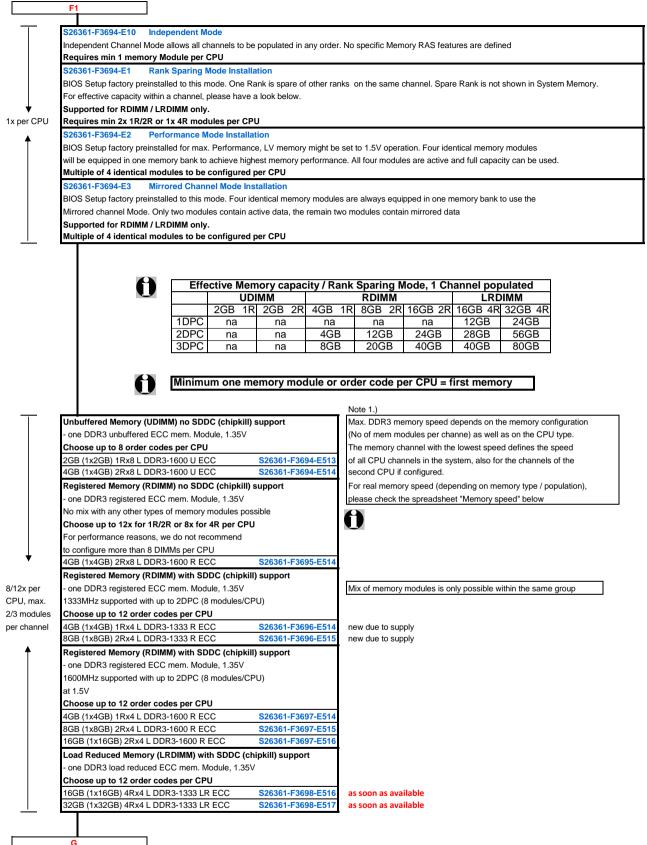






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d (e.g. E5-E2643, E5-26 is required. equired for a dual-proces	with a second CPU 667, E5-2680, E5-2690), the hot plug
	Note: Max. DDR3 Bus Speed depends on:
	- max. DDR3 Bus Speed from the CPU and
	- max. DDR3 Memory Speed and
	 max. memory modules on one memory channel
606264 E3605 E400	1
320301-F3083-E240	4
	4
320301-F3070-E230	4
606264 E3606 E000	1
320301-F3000-E290	4
606064 E0607 E000	1
520301-1 3007-2230	1
ink	
636361-E3600 E300	1
S26361-F3688-E180	3
320301-F3088-E18U	1
	S26361-F3685-E180 S26361-F3685-E240 S26361-F3685-E240 S26361-F3676-E230 S26361-F3676-E230 S26361-F3676-E250 S26361-F3686-E240 S26361-F3686-E240 S26361-F3686-E290 S26361-F3687-E300 S26361-F3687-E300 S26361-F3687-E300 S26361-F3687-E300 S26361-F3687-E300 S26361-F3687-E300 S26361-F3687-E290

Image: Second Secon		PRIMERGY TX300 S7 / RX350 S7 Status 2014-0
 • There are 12 memory slots per CPU for max. BackGE LRDIMM (12x 32GB 4R) 192GB RDIMM (12x 1GB 2R) 32GB WOMK (8x 4GF) • The memory area is divided into 4 channels per CPU i) using LRDIMM • The memory area is divided into 4 channels per CPU with 3 slots per channel • Slot 1 of each channel backings to memory bank 1, the slot 2 belongs to memory bank 2, slot 3 belongs to memory bank 3 Registered, LR DIMMs and unbuffered memory modules can be selected No mix of registered, Load reduced and unbuffered medules allowed. Memory can be operated at 1.5V or 1.35V, even if the modules are of low voltage type. Memory can be operated at 1.5V or 1.35V, even if the modules are supported: • 1.5V • 1600MHz max (depending on CPU) special memory modules (1.5V or 1.5V). SDDC (Chipkill) is supported for registered. Load reduced and unbuffered memory modules (1.5V or 1.5V). SDDC (Chipkill) is supported for registered. Load reduced and exceeding the composite of the set of the trans. • 1.5V • 1600MHz max (depending on CPU) In a 3 DIMMs per channel configuration, memory will operate at 1.5V only. SDDC (Chipkill) is supported for registered. Load reduced are composite Channels can be populated in any order an have no matching requirements. All cour channels may run at different DIMM timing (RFA) is latency. CAS 3 a valiable as system memory For the effective memory capacity, please refer to the spreadsheet below. The Spare Rank is held in even and is not valiable as system memory For the effective memory module opulation extra valiable as system memory For the effective memory module opulation extra valiable as system memory For the effective memory module population extra valiable as system memory bar the site directical modules in any order and 1.0 DRD 3 module per channel The BI	F	
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		192GB RDIMM (12x 16GB 2R)
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No mix of registered, load reduced and unbuffered modules allowed. Memory can be operated at 1.5V or 1.3SV, even if the modules are of low voltage type. Memory can be operated at 1.5V or 1.3SV, even if the modules are supported: 1.32 DIMMs per channel configuration, following frequencies are supported: 1.5V - 1600MHz max (depending on CPU) ha 3 DIMMs per channel configuration, memory modules) 1.3SV - 1333MHz max (depending on CPU) ha 3 DIMMs per channel configuration, memory modules of the supported for registered / load reduced x4 organized memory modules only SDDC (Chipkill) is supported for registered / load reduced x4 organized memory modules only channels can be populated in any order in Independent Channel Mode. All four channels must un at the same interface frequency but individual channels may run at different DIMM timing (RAS latency, and so forth) No mix of registered, load reduced and unbuffered modules allowed. 2) "Rank Sparing Mode" configuration • Within a memory channel, one rank is a spare of the other ranks. The ElOS is set to the rank sparing setting. Minimum configuration is : 2x 1R, 2x 2x or 1x14R DDR3 module per channel This mode is not supported by unbuffered memory modules 3) "Performance Mode" configuration • In this configuration is: x 1x 2x 2x or 1x14R DDR3 module per channel This mode is not supported by unbuffered memory modules		slot 3 belongs to memory bank 3
Memory can be operated at 1.5V or 1.35V, even if the modules are of low voltage type. Memory operating voltage can be set within BIOS (1.5V is default setting for max, speed). In a 2 DIMMs per channel configuration, following frequencies are supported: -1.5V - 1800MHz max (depending on CPU, special memory modules) -1.3V - 1800MHz max (depending on CPU, special memory will operate at 1.5V only. SDDC (Chipkill) is supported for registered / load reduced x4 organized memory modules only SDDC (Chipkill) is supported for registered / load reduced x4 organized memory modules only Channels can be populated in any order in Independent Channel Mode. All four channels may be populated in any order and have on matching requirements. All channels must un at the same interface frequency but individual channels may tru at different DIMM timings (RAS latency, CAS latency, and so forth) No mix of registered, load reduced and unbuffered modules allowed. 2.) "Rank Sparing Mode" configuration • Within a memory channel, one rank is a spare of the other ranks. The BIOS is set to the rank sparing setting. Minimum configuration is: 2x 2R or 1x4R DDR3 module per channel This mode is not supported by unbuffered memory modules 3.) "Performance Mode" configuration • In this configuration, its 4x 2R or 1x4R DDR3 module per channel This mode is not supported by unbuffered memory modules 3.) "Performance Mode" configuration		Registered, LR DIMMs and unbuffered memory modules can be selected
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		Minimum configuration is: 4x identical modules
		This mode is not supported by unbuffered memory modules
	F1	



Memory Configuration PRIMERGY TX300 S7 / RX350 S7

Each CPU offers 12 Slots for DDR3 Memory Modules organised in 3 Banks and 4 Channels. If you need more than 12 Slots you have to configure the 2nd CPU. Depending on the amount of memory configured you can decide between 4 basic modes of operation (see explanation below).

There are 3 different kinds of DDR3 Memory Modules available: UDIMM / RDIMM and LRDIMM UDIMM / RDIMM / LRDIMM offer different functionality. Mix of UDIMM / RDIMM / LRDIMM is not alloved.

If 1.5V and 1.35V DIMMs are mixed, the DIMMs will run at 1.5V

Mode	Configuration UDIMM RDIMM		RDIMM	Application	
		ODIMIM	RUIWIW	LRDIMM	
		x8	x8	x4	
SDDC (chipkill) support	any	no	no	yes	detect multi-bit errors
Independant Channel Mode	1, 2 or 3 Modules per Bank	yes	yes	yes	offers max. flexibility, upgradeability, capacity use UDIMM modules for lowest cost
Mirrored Channel Mode *)	4 identical Modules / Bank	no	no	yes	offers maximum security
Performance Mode	4 identical Modules / Bank	yes	yes	yes	offers maximum performance and capacity
Rank Sparing Mode *)	min. 2 Ranks / Channel	no	no	yes	balances security and capacity

*) For the delivery ex works the system will be prepared with dedicated BIOS setting

on special release

as soon as available

Capacity	Configuration	UDIMM	RDIMM	LRDIMM	Notes
Min. Memory per CPU	1 Module / CPU	1x2GB	1x4GB	1x 16GB	with one CPU
Max. Memory per CPU	8/12 Modules / CPU	8x4GB	12x16GB	12x 32GB	with one CPU
Max. Memory per System	16/24 Modules / System	64GB	384GB	768GB	if second CPU is configured

Memory-Speed:

Max. DDR3 memory speed depends on the memory configuration on one memory channel and the speed of the CPU The memory channel with the lowest speed defines the speed of all CPU channels in the system

Mem. Speed provided by CPU	Real maximum memory-bus speed depending on CPU type, memory configuration (DPC) and voltage setting (BIOS)																	
		UDI	MM 1	600N	/Hz			RD	IMM [·]	16001	ЛНz			LR	DIMM	1333	3MHz	
Voltage setting (BIOS)	1.5\	/ [defa	ault]		1.35\	/	1.5	/ [def	ault]		1.35\	/	1.5	V [def	ault]		1.35\	/
	1	2	3	1	2	3	1	2	3	1	2	3	1	2	3	1	2	3
	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC
CPU with 1600MHz DDR3 Bus	1333	1333	-	1066	1066	-	1600	1600	1066	1333	1333		1333	1333	1066	1066	1066	-
or o with roooming borto bus	1600		-	1333	1000	-	1000	1000	1000	1000	1000	-	1000	1000	1000	1000	1000	-
CPU with 1333MHz DDR3 Bus	1333	1333	-	1066	1066	-	1333	1333	1066	1333	1333	-	1333	1333	1066	1066	1066	-
CPU with 1066MHz DDR3 Bus	1066	1066	- /	1066	1066	-	1066	1066	1066	1066	1066	-	1066	1066	1066	1066	1066	-
P - Single Rank																		

1R - Single Rank

2R - Dual Rank

4R - Quad Rank

1DPC = 1 DIMM per Channel 2DPC = 2 DIMM per Channel

3DPC = 3 DIMM per Channel

Configuration hints:

- The memory sockets on the systemboard offer a color coding:

Bank I black sockets

Bank II blue sockets

Bank III green sockets

- A so called Bank consits of 1 memory module on every Channel available on one CPU (examples see below)

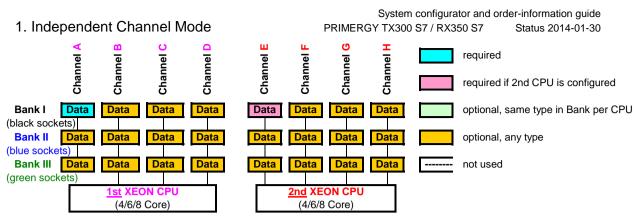
Bank I on CPU 1/2 up to 4 memory modules connected to Channel A - H on the 1st/2nd CPU Bank II on CPU 1/2

up to 4 memory modules connected to Channel A - E on the 1st/2nd CPU Bank III on CPU 1/2

up to 4 memory modules connected to Channel A - E on the 1st/2nd CPU

(can not be populated by UDIMM or 4R RDIMM memory modules)

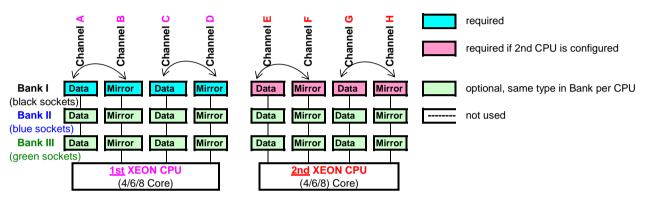
- See below and next page for a detailed descriptions of the memory configuration supported.



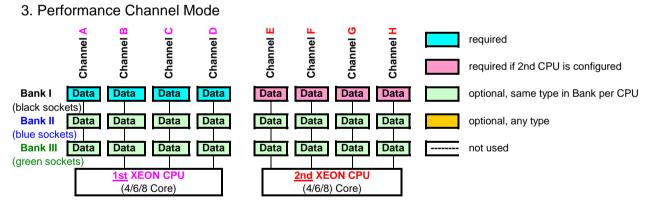
Independent Channel Mode allows all channels to be populated in any order

Can run with differently rated DIMMs and use the settings of the slowest DIMM installed in the system

2. Mirrored Channel Mode

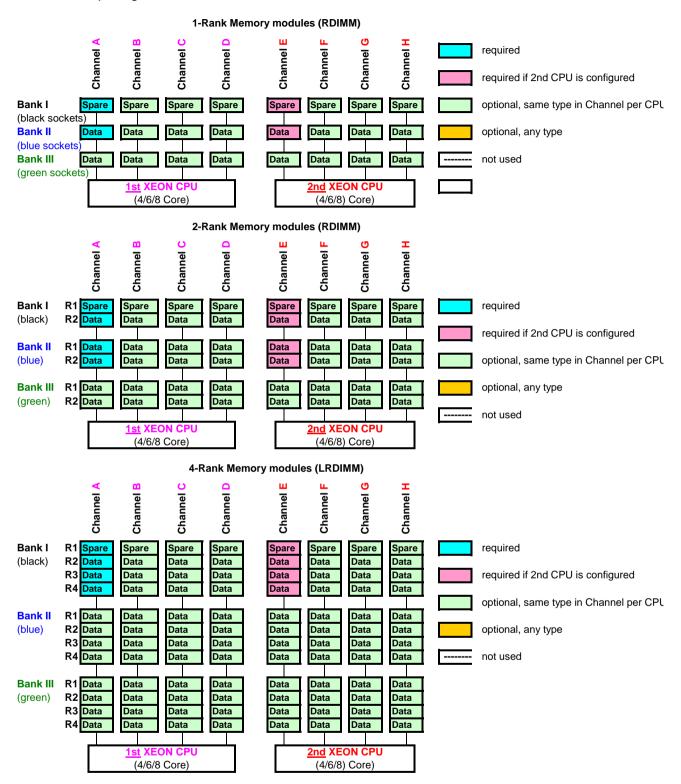


Mirrored Channel Mode requires identical modules on channel A,B, C, D (1st CPU) or channel E, F, G and H (2nd CPU) 50% of the capacity is used for the mirror => the available memory for applications is only half of the installed memory If this mode is used, a multiple of 4 identical modules has to be ordered.

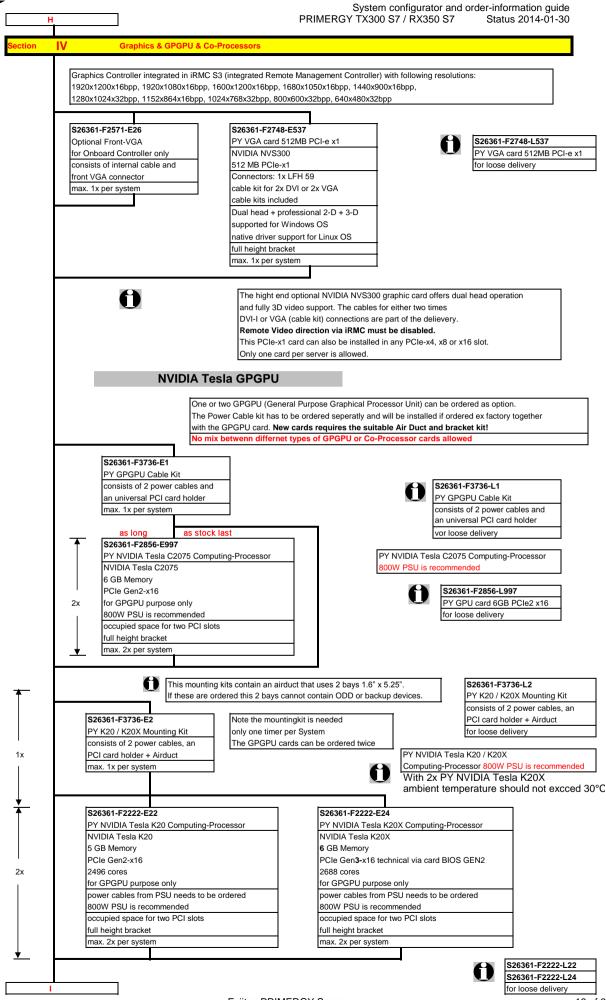


Performance Channel Mode requires identical modules on all channels of each Bank per CPU. If this mode is used, a multiple of 4 identical modules has to be ordered.

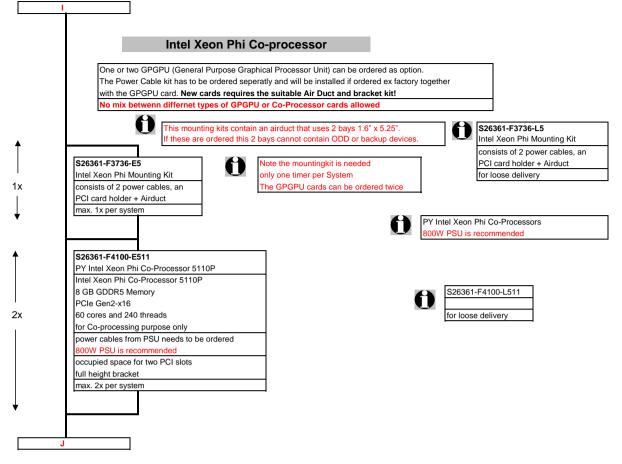
4. Rank Sparing Mode

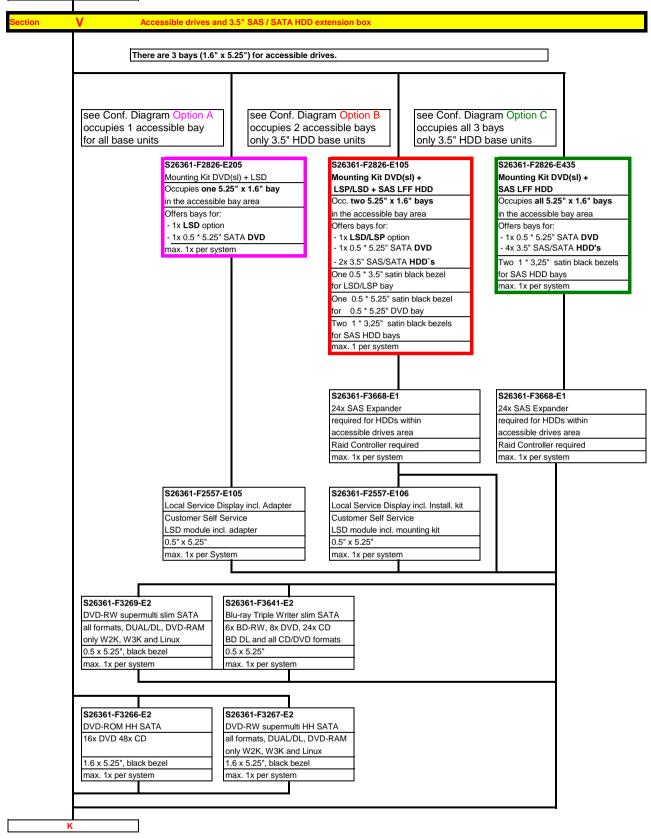


Rank Sparing Mode requires identical modules (same capacity and technology) within the same channel. The available memory for applications will vary depending on configuration. Please refer to the spreadsheet above "Effective Memory capacity with active Rank Sparing Mode". Population rule for Rank sparing mode is to achieve max. available memory, e.g. 6 DIMMs will be spread across two channels, each with 3DPC

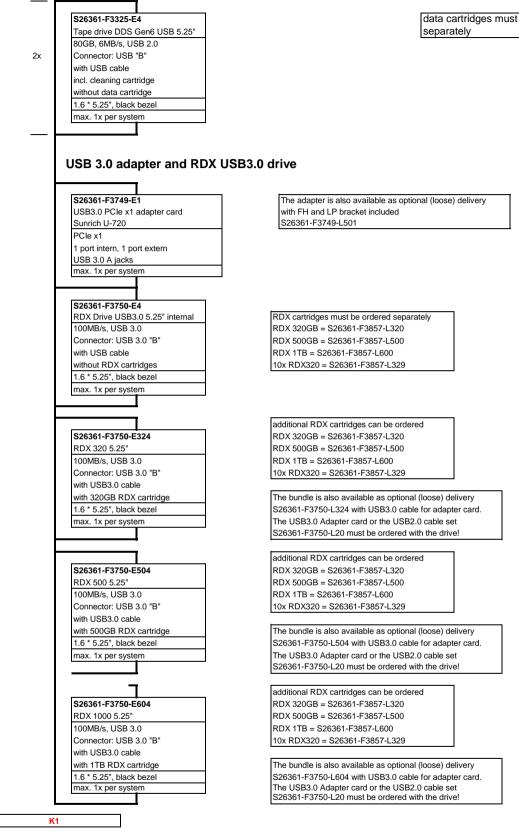


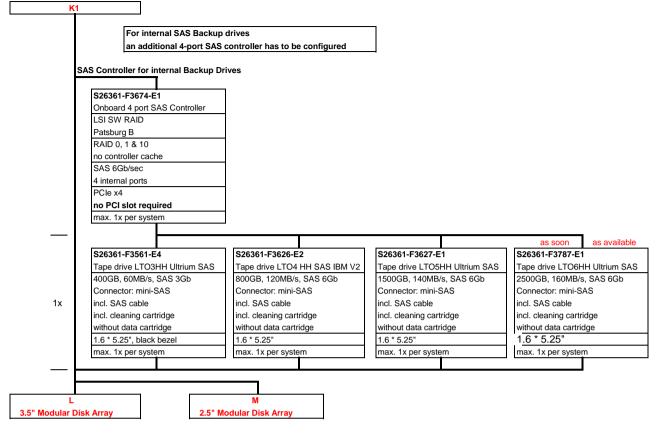
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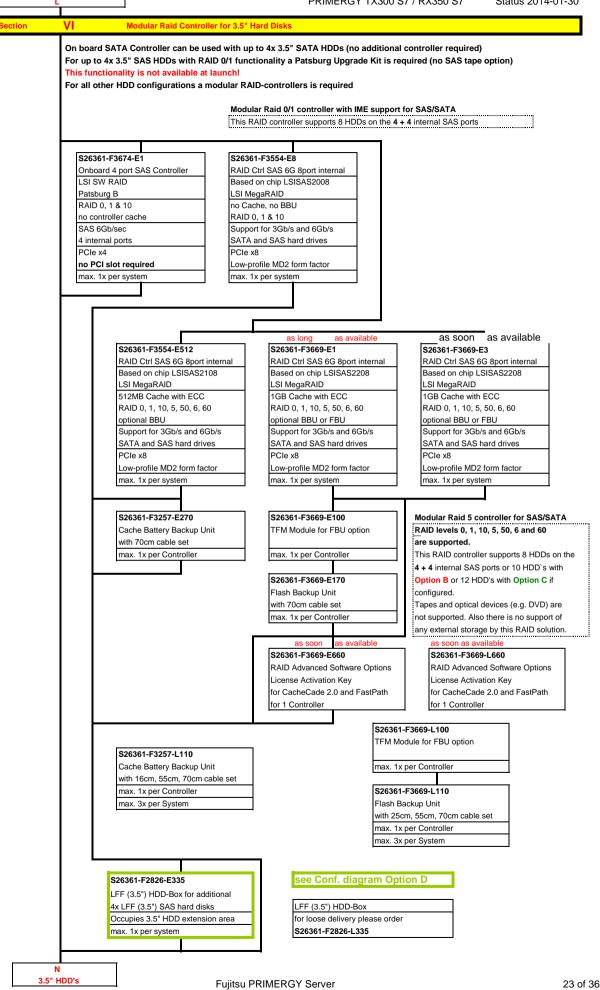


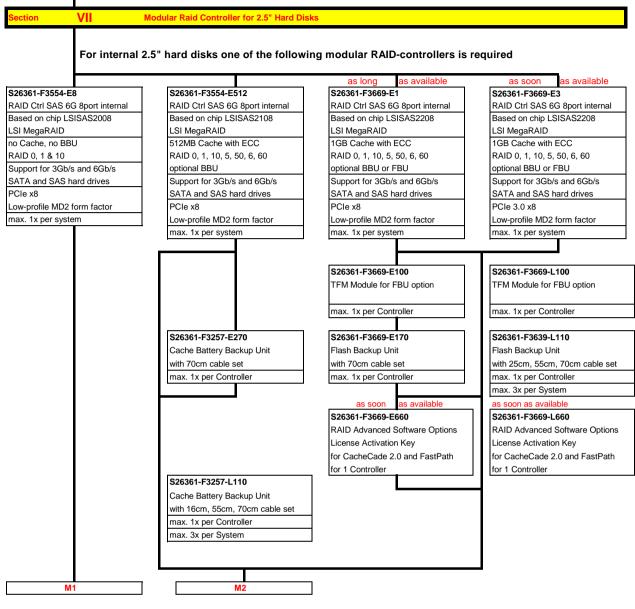


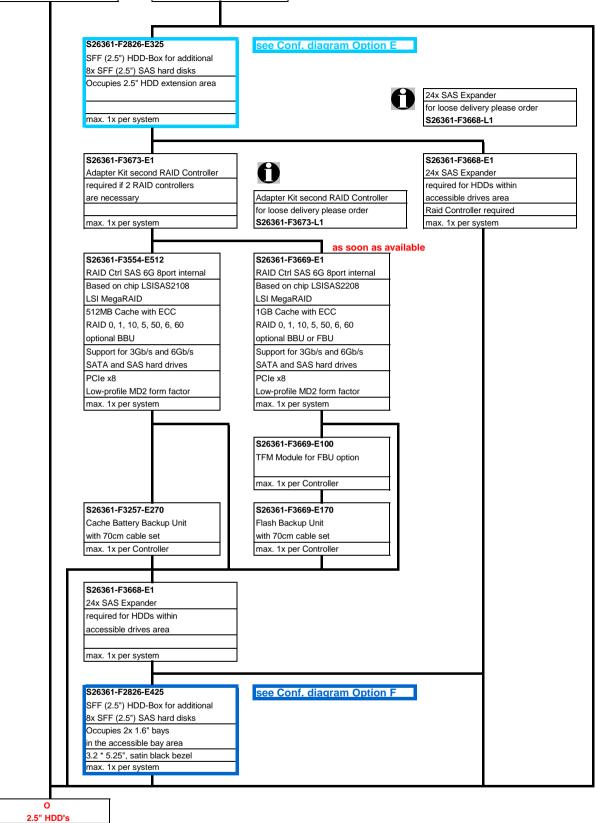
data cartridges must be ordered separately





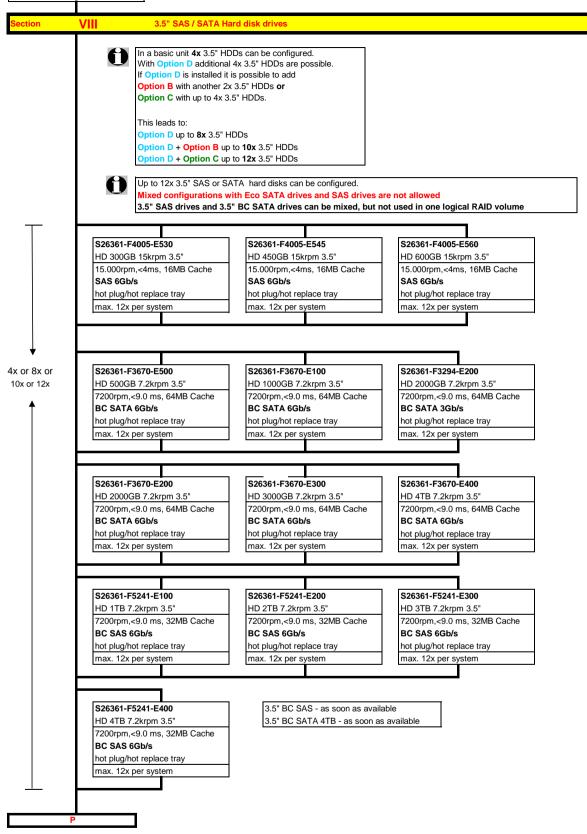


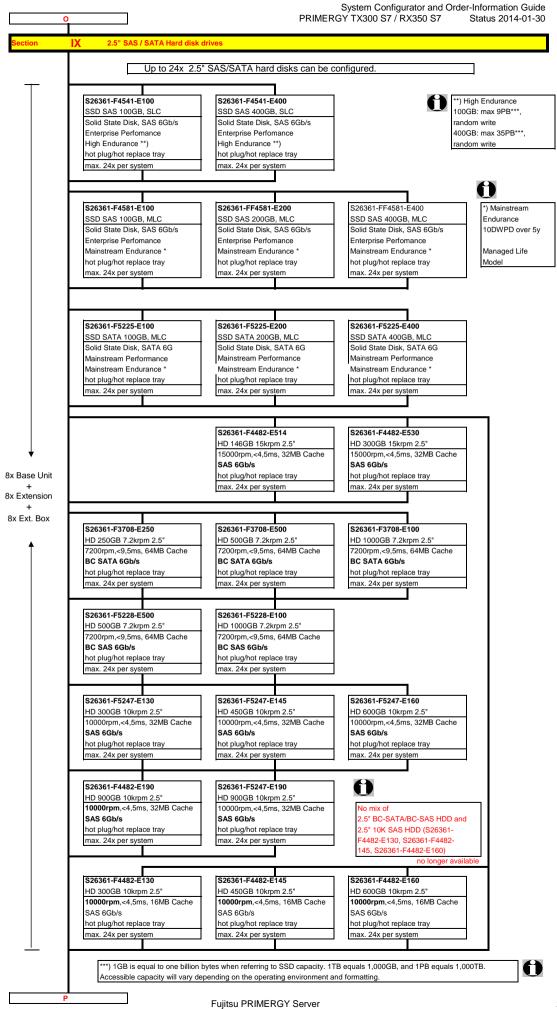


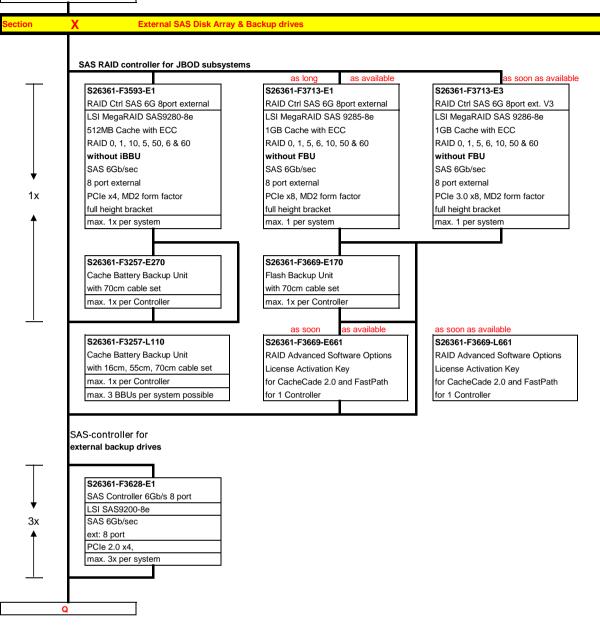


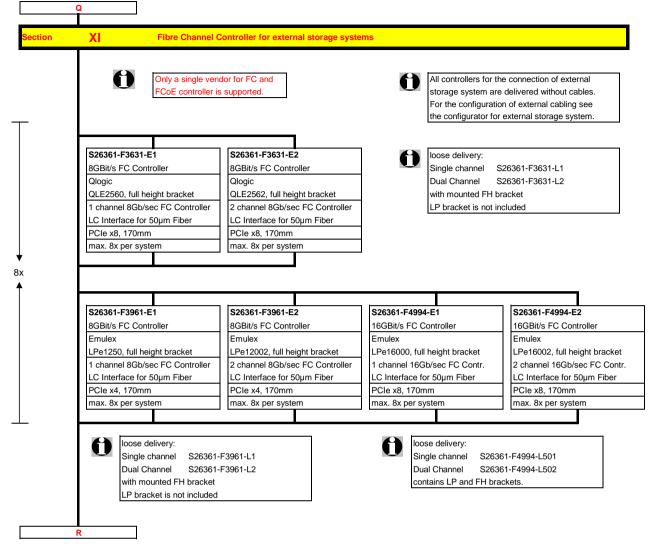
M2

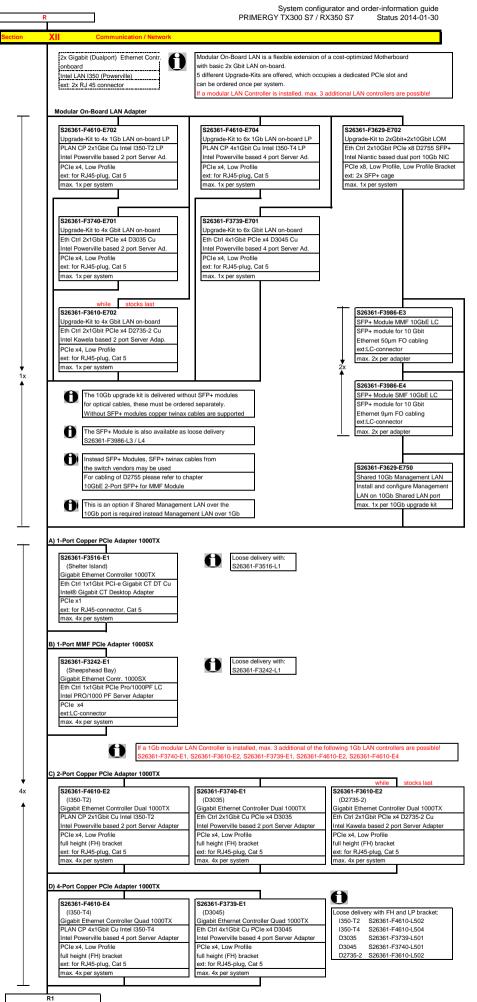
M1

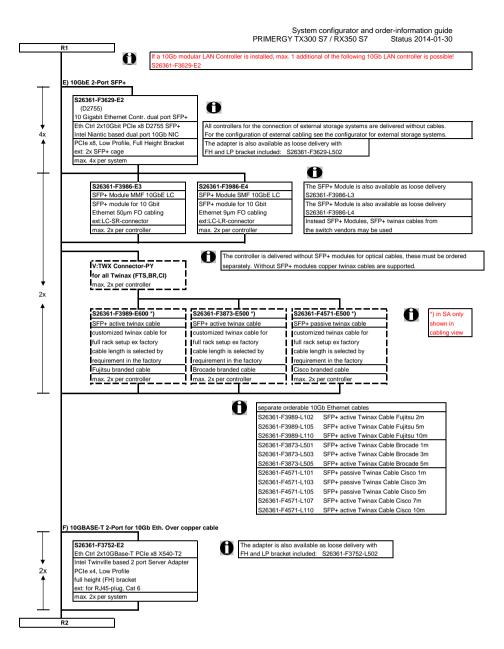




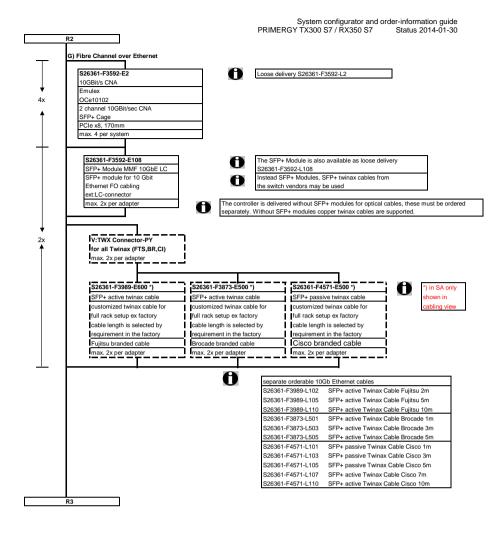


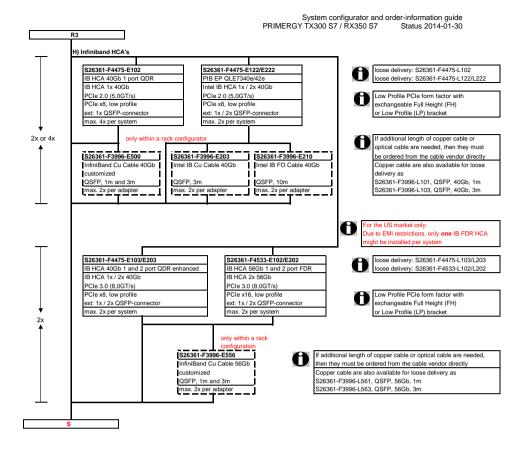


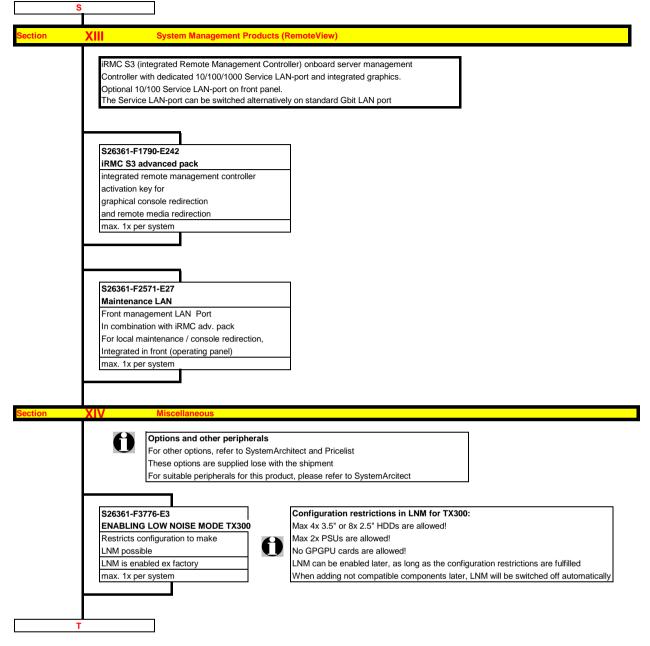


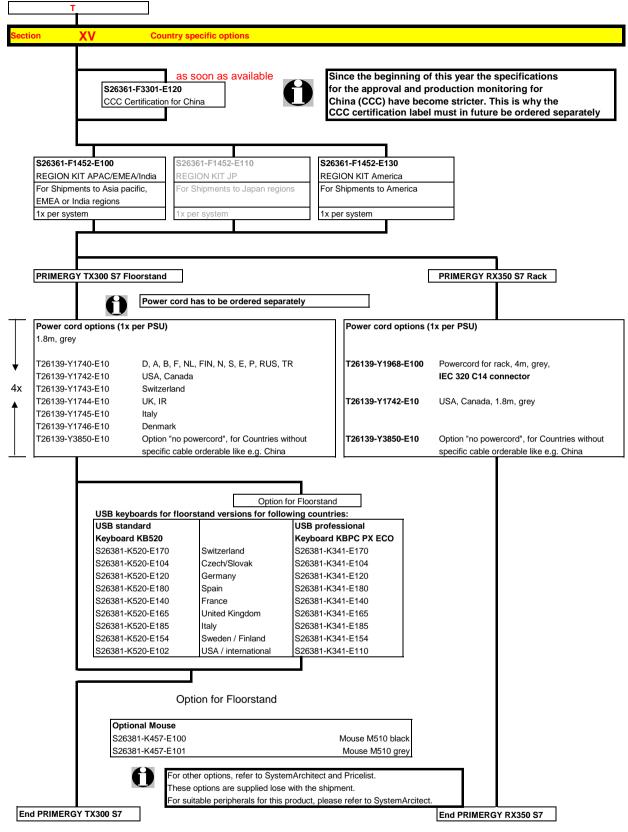


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Change Report

Date	Order number	Changes
2013-10-18	PCIe lenght	corrected
2013-10-18	Optional USB Comps	no longer available
2013-10-16	S26361-F4610-E2 / -E4	added new 1Gb NICs from Intel
2013-10-16	DDS5	removed from configurator due to EoL
2013-07-25		as long as stock last added for NVIDIA Tesla C2075
2013-05-28	S26361-F3787-E1	LTO6 added
2013-05-23	S26361-F3713-E3	RAID Ctrl SAS 6G 8Port ex 1GB LSI V3
2013-05-16	S26361-F4581-E100/E200/E400	New 2.5" SSD SAS 6G MLC added
2013-05-16	S26361-F3670-E400	New 3.5" BC-SATA 7.2K HDD 4TB
2013-05-16	S26361-F5241-E*	New 3.5" BC-SAS 7.2K HDD 1/2/3/4TB
2013-05-13		HDD & SSD description text updated
2013-05-13	S26361-F4482-E130/145/160	SAS HDD - no longer available
2013-05-07		GPGPU & Xeon Phi pages adjusted to "comp in sys" statements
2013-03-26	S26361-F3669-E660/L660	RAID advanced SW option added - for RAID Ctrl SAS 6G 1GB (D3116C)
2013-03-26	S26361-F3669-E3	RAID Ctrl SAS 6G 1GB (D3116C) added
2013-03-26	S26361-F3669-E661/L661	RAID advanced SW options added - for RAID Ctrl SAS 6G 8port external
2013-03-14	S26361-F3750-E324/504/E604	RDX & Cartridge bundles added
	Config. Diagram	Slot lenght corrected
2013-01-08	S26361-F5228-E***	New 2.5" BC-SAS 7.2K HDD
2013-01-08	S26361-F5247-E***	New 2.5" SAS 10K HDD (mix with BC-SATA supported, sucessor for *F5227*)
2012-12-13	S26361-F3585-E2	BD writer HH removed (EOL)
2012-12-13	S26361-F3641-E2	BD writer slim: "as soon as available" removed
2012-12-10	S26361-F3694-E3	"as soon as available" removed
2012-12-07	S26361-F2826-E105	HDD Box does not require LSD component any more
2012-12-07	S26381-K520-E170	new keyboard numbers introduced
2012-12-07	S26381-K457-E100	new mouse numbers introduced
2012-12-07	S26361-F3776-E3	ENABLING LOW NOISE MODE TX300 added
2012-12-06		added NVIDIA Tesla K20 & K20X and Intel Xeon Phi 5110P
2012-11-22	F3749-E4 and F3750-E4	"as soon as available" removed
2012-11-22	S26361-F3857-E4	"as long as available" added
	S26361-F3749-Ex	Added USB3.0 Adapter
	S26361-F3750-Ex	Added RDX Drive
2012-10-01	S26361-F3986-E4	
2012-10-01	S26361-F3740-E1/E701	New 4-port Intel LAN controller and upgrade kit - as soon as available
2012-10-01	S26361-F3739-E1/E701	New 2-port Intel LAN controller and upgrade kit - as soon as available
2012-09-28	S26361-F4541-E200	EOL: 200GB SSD SAS SLC
2012-09-11	S26361-F4522-Exxx	PCIe SSD (occupies PCIe slot) as soon as available deleted
2012-07-25	S26361-F4581-Exxx	Add SSD SAS MLC
	S26361-F3857-L160/L169	RDX Cartridge 160GB is EOL => removed
	S26361-F5227-E1*	New order for 2.5" 10K SAS HDD supporting mix with 2.5" BC-SATA HDD
	S26361-F3857-L160/L169	RDX Cartridge 160GB is EOL => removed
	S26361-F5225-E*00	New order for SATA SSD's
2012-05-08	S26361-F3753-E1	"Mounting Kit for 5,25" USB backup drives" added
2012-04-20		Memory voltage / frequency spreadsheet, 3DPC at 1.5V only
2012-03-30	S26361-F2735-L7	added, loose delivery of lateral cable management (GH)
2012-03-19	S26361-F3257-E270	change Cache Battery Backup -E170 to -E270
2012-03-09	S26361-F3700-E250/500	deleate 3,5" SATA 6Gb/s Economy HDs
2012-02-29		First release
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